

JAN 18 2002

TRANSMITTAL LETTER
(General - Patent Pending)

Docket No.
E0520CIP

In Re Application Of: Kashmir S. Sahota, Diana M. Schonauer, Johannes F. Groschopf, Gerd F.C. Marxsen, Steven A. Avanzino

Serial No.
09/749,191

Filing Date
December 26, 2000

Examiner
L. Umez-Eronini

Group Art Unit
1765

Title: "PREVENTION OF PRECIPITATION DEFECTS ON COPPER INTERCONNECTS DURING CMP BY USE OF SOLUTIONS CONTAINING ORGANIC COMPOUNDS WITH SILICA ADSORPTION AND COPPER CORROSION INHIBITING PROPERTIES"

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is:

Statement under 37 CFR 1.97(e) accompanying Information Disclosure Statement

Information Disclosure Statement

Cited Documents (4 documents)

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in the above identified application.

- No additional fee is required.
- A check in the amount of _____ is attached.
- The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. 01-0365 as described below. A duplicate copy of this sheet is enclosed.
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Dated: December 27, 2001

Deborah W. Wenocur
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Deborah W. Wenocur, Reg. No. 40,221

Agent for Applicant

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Deborah W. Wenocur
Signature of Person Mailing Correspondence

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STATEMENT UNDER 37 CFR 1.97(e) ACCOMPANYING
INFORMATION DISCLOSURE STATEMENT

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TO THE ASSISTANT COMMISSIONER FOR PATENTS:

This is a statement under the provisions of 37 CFR 1.97(e) in the above-identified application.

Check applicable statement herebelow:

Statement Under 37 CFR 1.97(e)(1)

- Each item of information contained in the accompanying Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

Statement Under 37 CFR 1.97(e)(2)

- No item of information contained in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned person, after making reasonable inquiry, no item of information contained in the accompanying Information Disclosure Statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the Information Disclosure Statement.

Deborah W. Wenocur
Signature

Dated: December 26, 2001

Deborah W. Wenocur, Reg. No. 40,221

Agent for Applicant

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